

# New Product Introduction June 2026



## POWER

[OptiMOS™ 8 power MOSFET 100 V](#)

[HybridPACK™ Drive G2 Fusion power module for traction inverter](#)

[OptiMOS™ 5 60 V switching optimized power MOSFETs](#)

[PROFET™ + 48V Automotive smart high-side switch](#)

[OptiMOS™ 7 40 V Dual SSO8 Automotive MOSFETs](#)

[HybridPACK™ Drive G2 SiC FS01M3R08A7MA2B, FS01M3R08A8MA2C, FS01M5R12A7MA2B, FS02MR08A7MA2B for EV inverter](#)

[FZ1200R45HL4 B8 4500 V, 1200 A single switch IGBT module in IHV B package](#)

## SENSOR TECHNOLOGY

[XENSIV™ BGT60CUTR13AIP Next-generation, ultra-low-power 60 GHz CMOS radar with integrated processing for IoT applications](#)

[XENSIV™ BGT60ATR24AIP 60 GHz radar sensor for reliable in-cabin monitoring systems](#)

## EVALUATION BOARDS

[EVAL\\_2KW\\_SiC\\_IH for high-frequency, 2 kW induction heating applications featuring CoolSiC™ MOSFET 650 V G2](#)

[EVAL-FFXMR12MM1H for EconoDUAL™ 3 power modules with CoolSiC™ technology](#)

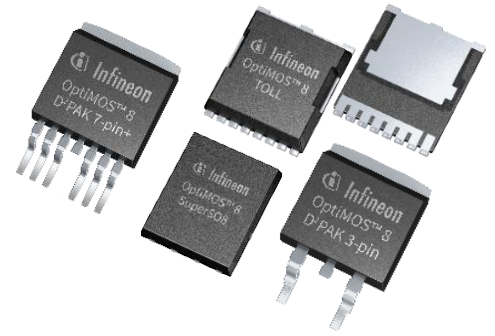
[REF-SMD5KIMSQM2INV motor-Integrated servo drive, powered by CoolSiC™ MOSFET 1200 V G2 in Q-DPAK half-bridge package](#)

## PLATFORMS

[AURIX™ DRIVECORE AUTOSAR \[Infineon, ETAS, TASKING\]](#)

## OptiMOS™ 8 power MOSFET 100 V

The new OptiMOS™ 8 power MOSFET 100 V technology, designed to address various motor control and battery protection applications with the need for lowest conduction losses. With industry's lowest  $R_{DS(on)}$  and excellent switching behavior, OptiMOS™ 8 100 V enables unmatched power density, system cost savings compared to its predecessor OptiMOS™ 5, all while maintaining next level capabilities and an outstanding price to performance ratio.



### Features

- > N-channel, normal level
- > Very low on-resistance  $R_{DS(on)}$
- > High ID current rating
- > Tight  $V_{GS(th)}$  spread
- > Soft body diode recovery and low  $Q_{rr}$
- > 100% avalanche tested
- > Pb-free lead plating; RoHS compliant
- > Halogen-free according to IEC61249-2-21
- > MSL 1 classified according to J-STD-020

### Competitive advantage

- > Price/performance optimized
- > Efficient power handling
- > Power density
- > High reliability

### Product collaterals / Online support

[Product family page](#)

### Benefits

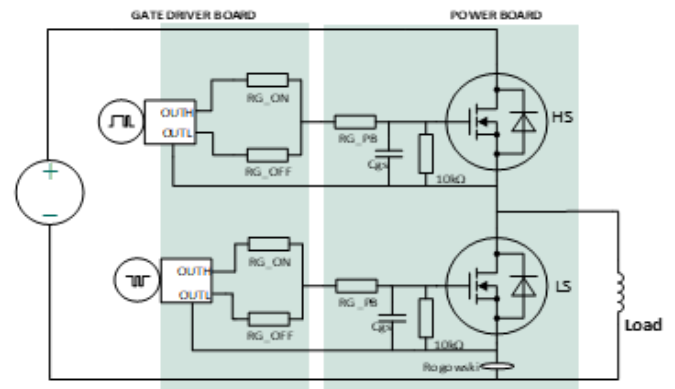
- > Lowest conduction losses through very low on-resistance  $R_{DS(on)}$  resulting in higher peak and steady-state current capability
- > Improved current sharing due to tight  $V_{GS(th)}$  spread
- > Excellent EMI behavior due to soft body diode
- > Ease of use

### Target applications

- > Drives
- > Battery management
- > Server
- > Telecom

### Block diagram

48 V servo drive



### Product overview incl. datasheet link

OPN	SP Number	Package
<a href="#">ISC019N10NM8ATMA1</a>	SP006114877	PG-TDSON-8
<a href="#">ISC033N10NM8ATMA1</a>	SP006114988	PG-TDSON-8
<a href="#">IPT009N10NM8ATMA1</a>	SP006114963	PG-HSOF-8
<a href="#">IPF009N10NM8ATMA1</a>	SP006114956	PG-TO263-7
<a href="#">IPF014N10NM8ATMA1</a>	SP006114974	PG-TO263-7
<a href="#">IPB018N10NM8ATMA1</a>	SP006114966	PG-TO263-3

## HybridPACK™ Drive G2 Fusion power module for traction inverter

Compact 750 V B6-bridge power module with Si/SiC Fusion switch optimized for traction inverters. The HybridPACK™ Drive G2 Fusion module combines the strengths of SiC and IGBT technologies to deliver a powerful, efficient and scalable solution for next-generation power electronics.



### Features

- > Blocking voltage: 750 V
- > Implemented current: 980 A / Repetitive peak current: 1960 A
- > Fusion switch: EDT3 IGBT/Diode and CoolSiC™ Gen2 MOSFET
- > Optimized for simultaneous gate drive
- > Advanced sintering die-attach technology
- > Integrated on-chip temperature sensor
- > Direct-cooled PinFin base plate
- > High-performance Si3N4 ceramic

### Benefits

- > Combination of SiC and IGBT/Diode to deliver a balanced trade-off between efficiency and cost-effectiveness
- > Low conduction and switching losses
- > High robustness over entire temperature range
- > Improved thermal conductivity

### Competitive advantage

- > Single-gate-drive operation for easy system integration
- > HybridPACK™ Drive footprint scalability, enabling fast time-to-market

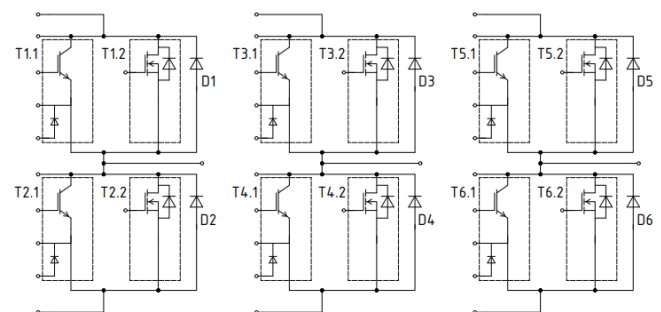
### Target applications

- > [EV traction inverter](#)
- > [Traction inverter \(electric commercial vehicles\)](#)
- > Automotive applications
- > (Hybrid) electrical vehicles (HEV)
- > Motor drives

### Product collaterals / Online support

[Product page](#)

### Block diagram



### Product overview incl. datasheet link

OPN	SP Number	Package
<a href="#">FS980R08A7F32BHPSA1</a>	SP006161968	AG-HDFSXT-3311

## OptiMOS™ 5 60 V switching optimized power MOSFETs

OptiMOS™ 5 60 V switching-optimized power MOSFETs in PQFN 5x6 Dual-Side Cooled drain-down package delivers low  $R_{DS(on)}$ , reduced switching losses, and strong thermal performance for AI, datacenter and telecom power conversion. The drain-down DSC 5x6 package enables high current density and compact power architectures, meeting efficiency, transient and reliability targets for GPU/accelerator rails in dense data-center servers.



### Features

- > PQFN 5x6, dual-side cooled package
- > Low  $R_{DS(on)}$
- > Induced turn on immunity, fast switching
- > Low-voltage overshoot
- > Low  $Q_g/Q_{oss}$  for high frequency operation
- > +175°C junction temperature rating

### Benefits

- > Ease of use
- > Highest system efficiency
- > Low conduction and switching losses
- > Higher conversion efficiency, less heat
- > Benchmark reliability
- > Increased power density

### Competitive advantage

- > Dedicated power MOSFETs for switching topologies
- > Industry leading  $R_{DS(on)}$  and FOMs
- > Ease of use
- > Improved reliability with temperature rating of +175°C
- > Superior thermal capabilities with high performance Dual Side Cooled package

### Target applications

- > AI data center
- > 48 V intermediate bus conversion
- > Server PSU
- > Telecom
- > Datacom
- > Motor Control
- > BMS

### Product collaterals / Online support

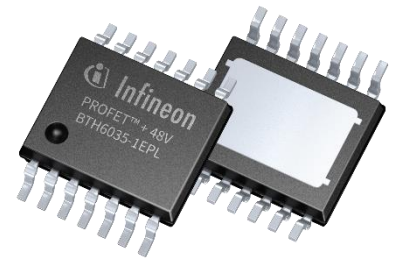
[Product family page](#)

### Product overview incl. datasheet link

OPN	SP Number	Package
<a href="#">ISC013N06NM5SCATMA1</a>	SP006183899	PG-WSON-8
<a href="#">ISC015N06NM5ATMA1</a>	SP006197204	PG-TDSON-8

## PROFET™ + 48V Automotive smart high-side switch

Infineon's 48 V smart high-side switches of the PROFET™ + 48V family are designed to be used for 48 V board nets. The family offers comprehensive protection functions, current sense diagnosis, 1/2/4-channels, an extended operating voltage range (up to 60 V) and high short-circuit robustness. All kinds of loads from 1 A to 5 A nominal load current can be driven. Some devices have adjustable current limitation and can switch capacitive loads.



### Features

- >  $R_{DS(on)}$  range 35-200 m $\Omega$
- > Up to 60 V operating range
- > Up to 4 channels
- > Automotive qualified, AEC-Q100
- > Enhanced energy capability
- > ISO 26262-ready
- > Analog current sense

### Benefits

- > Supporting evaluation acc. to ISO 26262
- > Suitable for 48 V systems
- > Providing protection and diagnosis
- > TDSO-8, TSDSO-14 and TSDSO-24 packages
- > Adjustable current limitation

### Competitive advantage

- > Reliable technology that has proven itself on the market for a long time
- > TSDSO-14 package with small footprint to minimize PCB area (-> 43% footprint reduction compared to TDSO-14 package)
- > Extended application range towards powertrain, chassis, fuel injection, pumps and industrial automation

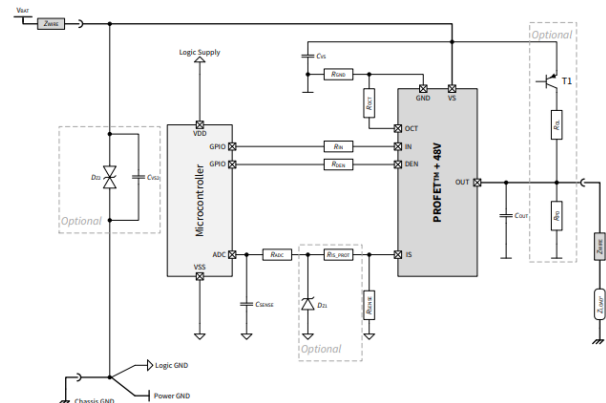
### Target applications

- > Electric vehicles
- > Mild hybrid vehicles
- > Industrial applications

### Product collaterals / Online support

[Product family page](#)

### Block diagram



### Product overview incl. datasheet link

OPN	SP Number	Package
<a href="#">BTH60351EPLXUMA1</a>	SP006145631	PG-TSDSO-14
<a href="#">BTH60702EPVXUMA1</a>	SP006145646	PG-TSDSO-14
<a href="#">BTH60801EPLXUMA1</a>	SP006145642	PG-TSDSO-14
<a href="#">BTH61002EPAXUMA1</a>	SP006145719	PG-TSDSO-14
<a href="#">BTH62001ENAXUMA1</a>	SP006033722	PG-TDSO-8
<a href="#">BTH62004ESAXUMA1</a>	SP006033726	PG-TSDSO-24

## OptiMOS™ 7 40 V Dual SSO8 Automotive MOSFETs

Our new OptiMOS™ 7 40 V Dual SSO8 Automotive MOSFET portfolio in 5x6 mm<sup>2</sup> is a high-performance solution for low to mid-power automotive applications, offering two integrated MOS channels with a current capability of 60 A each and a broad  $R_{DS(on)}$  range from 1.9 to 5.6 mΩ. The leadless design of the package minimizes stray inductance and package resistance, resulting in improved switching performance and robust system designs. The package is JEDEC-listed, making it a widely adoptable solution for various automotive applications.



### Features

- > Small 5x6 mm<sup>2</sup> footprint
- > High 60 A current capability
- > Leading-edge OptiMOS™ 7 40 V technology
- > Broad  $R_{DS(on)}$  range: 1.9 - 5.6 mΩ
- > Leadless package with Cu-clip for minimized package resistance and stray inductance

### Benefits

- > High power density and efficiency
- > Increased current capability
- > Reduced conduction losses
- > High thermal capacity lead-frame package
- > Superior switching performance
- > Reduced form factor vs. traditional leaded packages
- > Industry standard package (JEDEC "PG-TDSON-8")

### Competitive advantage

- > New Dual SSO8 5x6 mm<sup>2</sup> package with copper clip for increased current and avalanche capability
- > OptiMOS™ 7 technology for best-in-class  $R_{DS(on)}$  performance and optimized switching performance
- > Automotive quality product design with leading 300 mm in-house production

### Target applications

- > Power lift gate
- > Window lift
- > Water pump
- > Electric parking brake
- > Power seat
- > Body control modules
- > Small BLDC drives

### Product collaterals / Online support

[Promo page](#)

[Product family page](#)

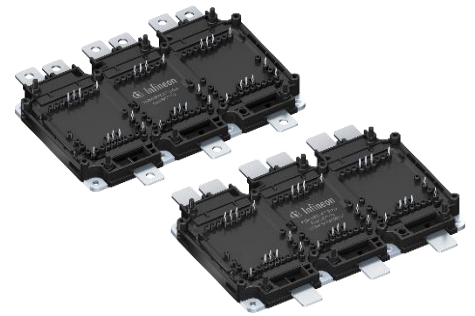
### Product overview incl. datasheet link

OPN	SP Number	Package
<a href="#">IAUCN04S7L018DATMA1</a>	SP006020219	PG-TDSON-8
<a href="#">IAUCN04S7N019DATMA1</a>	SP005728242	PG-TDSON-8
<a href="#">IAUCN04S7L024DATMA1</a>	SP006020223	PG-TDSON-8
<a href="#">IAUCN04S7N024DATMA1</a>	SP005728244	PG-TDSON-8
<a href="#">IAUCN04S7L038DATMA1</a>	SP006020227	PG-TDSON-8

## HybridPACK™ Drive G2 SiC FS01M3R08A7MA2B, FS01M3R08A8MA2C, FS01M5R12A7MA2B, FS02MR08A7MA2B for EV inverter

The HybridPACK™ Drive G2 is a compact B6-bridge power module optimized for traction inverter applications, offering scalability up to 300 kW within the 750 V and 1200 V class.

The product is available with different current ratings, voltage levels and Infineon's next generation chip technologies CoolSiC™ G2 MOSFET. HybridPACK™ Drive G2 additionally provides new features for optimal system cost, such as an integration option for next-generation phase current sensor.



### Features

- > Low  $R_{DS(on)}$
- > Low switching losses
- > Low  $Q_g$  and  $Cr_{ss}$
- >  $T_{vj,op} = 175^{\circ}C$  (short-time  $T_{vj,op} = 200^{\circ}C$ )
- > 4.2 kV DC 1 second insulation
- > High power density
- > Direct-cooled PinFin base plate
- > Integrated temp sensing diode

### Benefits

- > Higher temperature cycling capability
- > Integrated diode temperature sensors
- > New plastic material for better temperature capability
- > New frame design for lower system BOM
- > Lower AC contact resistance and tab temperature
- > RoHS compliant
- > Completely Pb free
- > Superior reliability

### Competitive advantage

- > Enable scalable inverter platform development
- > Superior gate oxide and cosmic ray reliability
- > Improved thermal conductivity
- > High robustness over entire temperature range
- > Increased durability especially in harsh environment

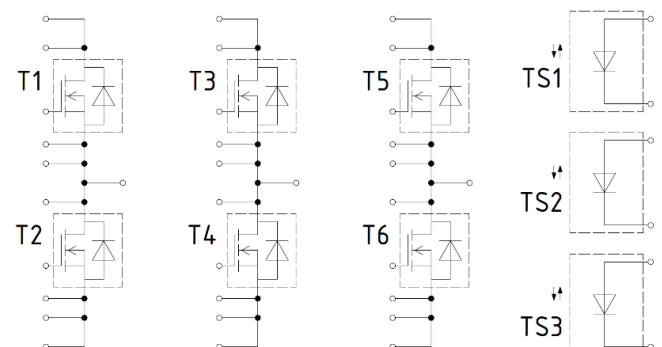
### Target applications

- > Automotive traction inverter
- > CAV traction inverter

### Product collaterals / Online support

[Product family page](#)

### Block diagram



### Product overview incl. datasheet link

OPN	SP Number	Package
<a href="#">FS01M3R08A7MA2BHPSA1</a>	SP006157550	AG-HDG2XT-3311
<a href="#">FS01M5R12A7MA2BHPSA1</a>	SP006157483	AG-HDG2XT-3311
<a href="#">FS02MR08A7MA2BHPSA1</a>	SP006157492	AG-HDG2XT-3311

## FZ1200R45HL4\_B8 4500 V, 1200 A single switch IGBT module in IHV B package

IHV 4500 V, 1200 A 130 mm single switch IGBT module with IGBT4 Trench field stop technology is the most suitable solution for your HVDC, Statcom and industry applications.



### Features

- > Low VCE(sat)
- > AISiC Base Plate
- > Storage temperature down to = -40°C
- > Package with CTI > 600

### Benefits

- > Enabling compact inverter designs
- > Low power losses
- > Standardized housing
- > Long life

### Competitive advantage

- > High performance
- > Low losses
- > Robust and reliable

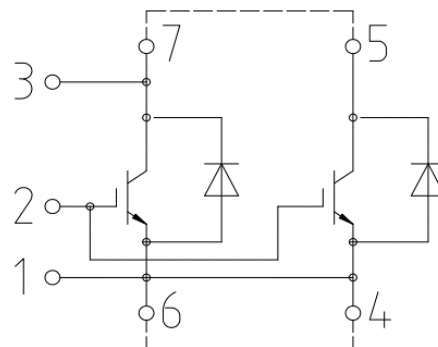
### Target applications

- > HVDC
- > Statcom
- > Drives

### Product collaterals / Online support

[Product page](#)

### Block diagram



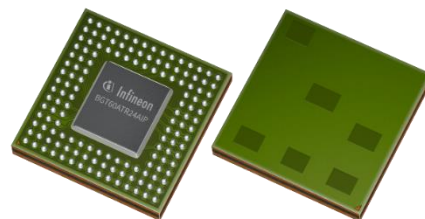
### Product overview incl. datasheet link

OPN	SP Number	Package
<a href="#">FZ1200R45HL4B8BPSA1</a>	SP006170748	AG-IHVB130-411



## XENSIV™ BGT60ATR24AIP 60 GHz radar sensor for reliable in-cabin monitoring systems

The BGT60ATR24AIP is Infineon's highly integrated automotive-grade 60 GHz FMCW radar sensor with an antenna-in-package (AIP) designed for short-range in-vehicle sensing. It offers advanced sensing with high precision and ultra-low power consumption, making it ideal for enabling contactless in-cabin monitoring with very high accuracy, easy integration, and low system cost.



### Features

- > 60 GHz radar for FMCW operation
- > 8.0 × 8.0 × 0.86 mm<sup>3</sup> package size
- > Antennas-in-Package (AIP)
- > Ultra-low power consumption
- > AEC-Q100, Grade 2 qualified
- > High bandwidth of 4.7 GHz
- > Built-in crystal oscillator

### Benefits

- > High resolution and sub-cm accuracy
- > Micro-motion detection with steep chirps
- > Reliable azimuth and elevation sensing
- > Low power with minimal MCU involvement
- > Autonomous FSM reduces power usage
- > Robust spatial sensing with 2 Tx / 4 Rx

### Competitive advantage

- > Large bandwidth of 4.7 GHz enables high range resolution for multiple person detection in a car and precise micro-motion sensing
- > Antenna-in-Package accelerates time to market, reduces system cost and simplifies integration
- > Detects presence and micro-motions in occluded areas such as footwells and under blankets
- > Autonomous FSM minimizes MCU involvement for ultra-low power consumption
- > 2 Tx / 4 Rx configuration delivers reliable azimuth and elevation sensing
- > AEC-Q100 Grade 2 qualified for automotive environments
- > Reduces external component count and simplifies system

### Target applications

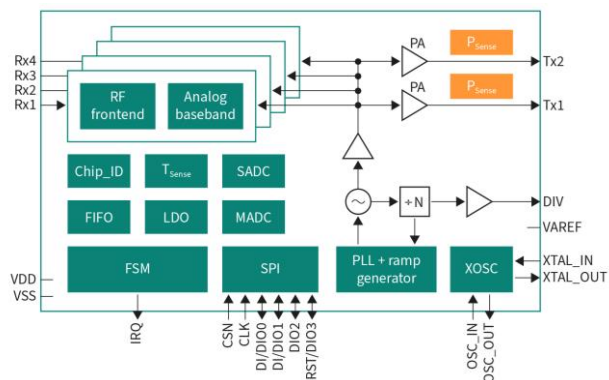
- > [In-cabin monitoring system \(ICMS\)](#)

### Product collaterals / Online support

[Product page](#)

### Block diagram

Block diagram: BGT60ATR24AIP



### Product overview incl. datasheet link

OPN	SP Number	Package
<a href="#">BGT60ATR24AIP6327XUMA1</a>	SP005729106	PG-VF2BGA-144

## EVAL\_2KW\_SiC\_IH for high-frequency, 2 kW induction heating applications featuring CoolSiC™ MOSFET 650 V G2

The evaluation board EVAL\_2KW\_SiC\_IH features the new CoolSiC™ MOSFETs 650 V G2 family, specifically designed for induction heating and resonant switching applications up to 150 kHz. It demonstrates the functionality and key features of the CoolSiC™ MOSFETs G2 in combination with the level-shift EiceDRIVER™ gate driver ICs based on SOI technology.



### Features

- > 99.7% ultra-high efficiency at 2 kW
- > 1.3 – 1.8% higher efficiency compared to IGBT solutions
- > High switching frequency operation at 100 kHz to 150 kHz

### Benefits

- > Potential elimination of cooling fans
- > System cost savings and higher reliability
- > Power reduction of AUX power supply
- > Reduction of passive components

### Competitive advantage

- > Evaluation board for evaluation and measurement of characteristics and proof of datasheet specifications for CoolSiC™ MOSFET 650 V G2 and EiceDRIVER™ 2ED2x
- > Demonstrates capability and functionality of SiC MOSFETs and gate driver ICs in resonant induction heating applications for switching frequencies up to 150 kHz
- > Potential elimination of cooling fans, which results in system cost savings and higher reliability
- > Significant power reduction of auxiliary power supplies design

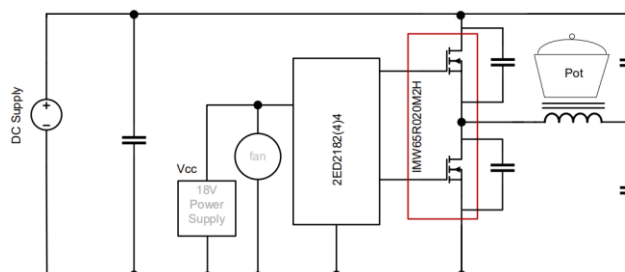
### Target applications

- > [Induction cooking](#)

### Product collaterals / Online support

[Board page](#)

### Block diagram



### Product overview incl. application notes link

OPN	SP Number	Package
<a href="#">EVAL2KWSICIH01</a>	SP006232449	LG-MADK-1

# EVAL-FFXMR12MM1H for EconoDUAL™ 3 power modules with CoolSiC™ technology

EVAL-FFXMR12MM1H evaluation board enables fast evaluation of EconoDUAL™ 3 power modules with CoolSiC™ technology, such as FF1MR12MM1H\_B11. EVAL FFXMR12MM1H includes the EiceDRIVER™ providing DESAT short-circuit protection and active Miller clamping. The evaluation board is equipped with an internal gate-driver voltage supply and an NTC thermistor for measuring temperature.



## Features

- > Isolated internal power supply (15 V and 5 V)
- > NTC temperature measurement
- > Active Miller clamping and DESAT detection
- > PCB suitable for PressFIT mounting
- > Two selective gate voltage levels
- > Isolated gate driver with optional booster stage

## Benefits

- > Self-supplying via internal power supply
- > Short-circuit protection via DESAT detection
- > Prevention of dynamic self-turn-on via active Miller clamping
- > Gate voltage levels: +18 V/-3 V or 15/-5 V

## Competitive advantage

- > High switching frequency
- > Reduced volume and size
- > Reduction of system costs
- > High thermal efficiency

## Target applications

- > HVAC control
- > eCAV
- > Energy storage systems
- > Motor control / GPD
- > Uninterruptible power supply

## Product collaterals / Online support

[Board page](#)

## Block diagram

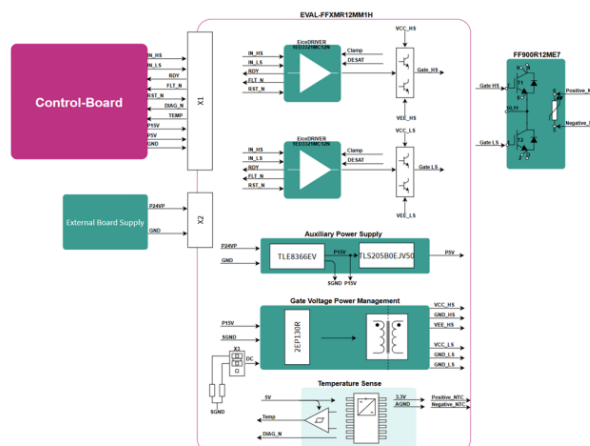


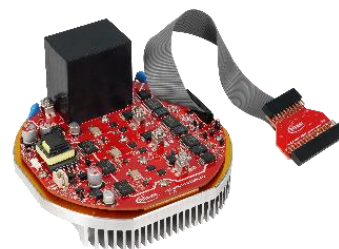
Figure 2 Structural block diagram of EVAL-FFXMR12MM1H

## Product overview incl. user guide link

OPN	SP Number	Package
<a href="#">EVALFFXMR12MM1HTOBO1</a>	SP006111406	--

## REF-SMD5KIMSQM2INV motor-Integrated servo drive, powered by CoolSiC™ MOSFET 1200 V G2 in Q-DPAK half-bridge package

This innovative design for a 3-phase motor-integrated servo drive combines efficient top-side cooling of discrete Q-DPAK half-bridge packages with Infineon's advanced 1200 V CoolSiC™ MOSFET G2 technology, enabling compact and cost-effective motor-integrated servo drive solutions with reduced complexity and increased efficiency.



### Features

- > 6.5 kW 3-phase motor-integrated drive
- > For 350 – 800 V DC input voltage
- > Top-side cooled approach with Q-DPAK
- > Single-board compact solution
- > 1200 V CoolSiC™ MOSFET G2 technology
- > Isolated EiceDRIVER™ with DESAT

### Benefits

- > Ultra-compact, minimized footprint
- > Lower cost via simplified assembly
- > Better electrical efficiency
- > Passive cooling; small heatsink
- > HW based short-circuit protection

### Competitive advantage

- > Smaller, simpler motor integrated servo drives—enabled by CoolSiC™ Gen2 Q-DPAK + EiceDRIVER™ F3
- > Lower cost and simpler build: single FR4 PCB, no IMS board, simplified assembly; delivers strong thermal performance via top side cooled Q-DPAK
- > Higher power density with passive cooling: high efficiency reduces losses, enabling a small heatsink and motor integration form factors
- > Robust, clean switching and protection: reduced stray inductance for better gate control and EMI behavior, plus DESAT-based short circuit protection for reliable operation with SiC

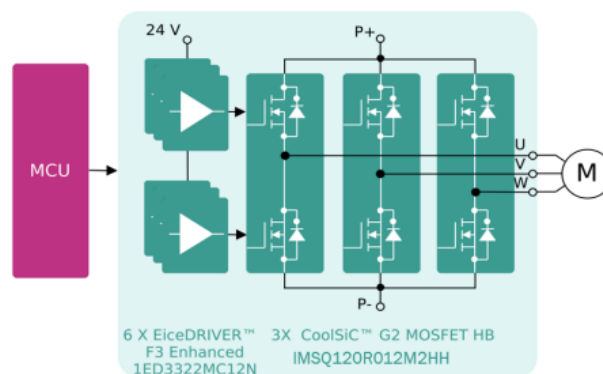
### Target applications

- > [Servo motor drive and control](#)
- > [Robotics](#)

### Product collaterals / Online support

[Board page](#)

### Block diagram

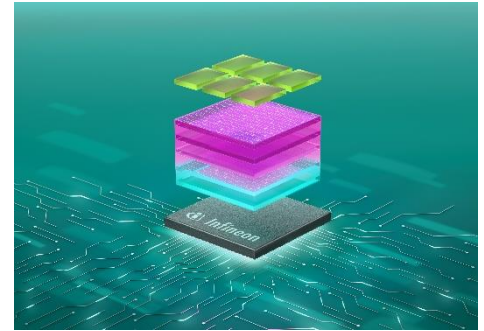


### Product overview incl. user guide link

OPN	SP Number	Package
<a href="#">REFSMD5KIMSQM2INVT0B01</a>	SP006179634	--

## AURIX™ DRIVECORE AUTOSAR [Infineon, ETAS, TASKING]

AURIX™ DRIVECORE AUTOSAR [Infineon, ETAS, TASKING] is a software bundle that accelerates development of AUTOSAR ECU with optimized footprint. It includes Infineon's MC-ISAR MCAL, ETAS RTA-CAR Classic SDK, and RTA-HVR hypervisor, supported by TASKING TC4x toolchain.



### Features

- > Infineon's MCAL driver: standardized interface to the AURIX™ microcontroller
- > RTA-CAR: high-performance, low-footprint, extensively configurable AUTOSAR classic basic software solution
- > TASKING's TC4x Tool Chain SmartCode: comprehensive C/C++ development environment for TriCore and PPU
- > ISO26262 and ISO/SAE21434

### Benefits

- > Small and fast: optimized to work in the most resource-constrained, low-latency real-time production environments
- > Reduced license complexity

### Competitive advantage

- > Pre-integrated software stack for accelerating automotive software development
- > One unique license agreement

### Target applications

- > ADAS, Chassis, E/E architectures, Domain Control, Zone Control, Powertrain, BMS, other safety critical systems
- > Supported Hardware: AURIX™ TC4D9XP COM Triboard

### Product collaterals / Online support

[Product page](#)